

Title (en)

CURING COMPOSITION FOR AN EPOXY RESIN COMPOSITION, EPOXY RESIN COMPOSITION, AND MULTI-COMPONENT EPOXY RESIN SYSTEM WITH IMPROVED LOW TEMPERATURE CURING

Title (de)

HÄRTERZUSAMMENSETZUNG FÜR EINE EPOXIDHARZMASSE, EPOXIDHARZMASSE UND MEHRKOMPONENTEN-EPOXIDHARZSYSTEM MIT VERBESSERTER TIEFTEMPERATURHÄRTUNG

Title (fr)

COMPOSITION DE DURCISSEUR POUR RÉSINE ÉPOXYDE, RÉSINE ÉPOXYDE ET SYSTÈME DE RÉSINE ÉPOXYDE À PLUSIEURS COMPOSANTS AYANT UN MEILLEUR DURCISSEMENT À BASSE TEMPÉRATURE

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Application

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Abstract (en)

[origin: CA3132925A1] The invention relates to a curing composition for a multi-component epoxy resin composition for chemically fixing construction elements, an epoxy resin composition and a multi-component epoxy resin system. The invention further relates to a method for chemically fixing construction elements in boreholes. The invention also relates to the use of a combination of a salt (S) with a phenol derivative for chemically fixing construction elements, in particular at low temperatures (= 0 °C), for improving the curing and the extraction resistance.

IPC 8 full level

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Citation (search report)

See references of WO 202221608A1

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